

DIGITAL INTEGRATED CIRCUITS

A DESIGN PERSPECTIVE
SECOND EDITION

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Contents

Preface

vii

Part 1	The Fabrics	1
<hr/>		
Chapter 1	Introduction	3
1.1	A Historical Perspective	4
1.2	Issues in Digital Integrated Circuit Design	6
1.3	Quality Metrics of a Digital Design	15
1.3.1	Cost of an Integrated Circuit	16
1.3.2	Functionality and Robustness	18
1.3.3	Performance	27
1.3.4	Power and Energy Consumption	30
1.4	Summary	31
1.5	To Probe Further	31
	Reference Books	32
	References	33
Chapter 2	The Manufacturing Process	35
2.1	Introduction	36
2.2	Manufacturing CMOS Integrated Circuits	36
2.2.1	The Silicon Wafer	37
2.2.2	Photolithography	37
2.2.3	Some Recurring Process Steps	41
2.2.4	Simplified CMOS Process Flow	42
2.3	Design Rules—The Contract between Designer and Process Engineer	47
2.4	Packaging Integrated Circuits	51
2.4.1	Package Materials	52
2.4.2	Interconnect Levels	53
2.4.3	Thermal Considerations in Packaging	59
2.5	Perspective—Trends in Process Technology	61
2.5.1	Short-Term Developments	61
2.5.2	In the Longer Term	63

2.7	To Probe Further	64
	References	64
<i>Design Methodology Insert A IC LAYOUT</i>		67
A.1	To Probe Further	71
	References	71
<i>Chapter 3 The Devices</i>		73
3.1	Introduction	74
3.2	The Diode	74
3.2.1	A First Glance at the Diode—The Depletion Region	75
3.2.2	Static Behavior	77
3.2.3	Dynamic, or Transient, Behavior	80
3.2.4	The Actual Diode—Secondary Effects	84
3.2.5	The SPICE Diode Model	85
3.3	The MOS(FET) Transistor	87
3.3.1	A First Glance at the Device	87
3.3.2	The MOS Transistor under Static Conditions	88
3.3.3	The Actual MOS Transistor—Some Secondary Effects	114
3.3.4	SPICE Models for the MOS Transistor	117
3.4	A Word on Process Variations	120
3.5	Perspective—Technology Scaling	122
3.6	Summary	128
3.7	To Probe Further	129
	References	130
<i>Design Methodology Insert B Circuit Simulation</i>		131
	References	134
<i>Chapter 4 The Wire</i>		135
4.1	Introduction	136
4.2	A First Glance	136
4.3	Interconnect Parameters—Capacitance, Resistance, and Inductance	138
4.3.1	Capacitance	138
4.3.2	Resistance	144
4.3.3	Inductance	148
4.4	Electrical Wire Models	150
4.4.1	The Ideal Wire	151
4.4.2	The Lumped Model	151
4.4.3	The Lumped <i>RC</i> Model	152
4.4.4	The Distributed <i>rc</i> Line	156
4.4.5	The Transmission Line	159

Contents		xvii
4.5	SPICE Wire Models	170
4.5.1	Distributed rc Lines in SPICE	170
4.5.2	Transmission Line Models in SPICE	170
4.5.3	Perspective: A Look into the Future	171
4.6	Summary	174
4.7	To Probe Further	174
	References	174

Part 2	A Circuit Perspective	177
---------------	------------------------------	------------

Chapter 5	The CMOS Inverter	179
------------------	--------------------------	------------

5.1	Introduction	180
5.2	The Static CMOS Inverter—An Intuitive Perspective	180
5.3	Evaluating the Robustness of the CMOS Inverter: The Static Behavior	184
5.3.1	Switching Threshold	185
5.3.2	Noise Margins	188
5.3.3	Robustness Revisited	191
5.4	Performance of CMOS Inverter: The Dynamic Behavior	193
5.4.1	Computing the Capacitances	194
5.4.2	Propagation Delay: First-Order Analysis	199
5.4.3	Propagation Delay from a Design Perspective	203
5.5	Power, Energy, and Energy Delay	213
5.5.1	Dynamic Power Consumption	214
5.5.2	Static Consumption	223
5.5.3	Putting It All Together	225
5.5.4	Analyzing Power Consumption Using SPICE	227
5.6	Perspective: Technology Scaling and its Impact on the Inverter Metrics	229
5.7	Summary	232
5.8	To Probe Further	233
	References	233

Chapter 6	Designing Combinational Logic Gates in CMOS	235
------------------	--	------------

6.1	Introduction	236
6.2	Static CMOS Design	236
6.2.1	Complementary CMOS	237
6.2.2	Ratioed Logic	263
6.2.3	Pass-Transistor Logic	269
6.3	Dynamic CMOS Design	284
6.3.1	Dynamic Logic: Basic Principles	284

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